

### ABSTRACT OF THE DISCLOSURE

A polishing apparatus has a polishing table having a polishing surface, a top ring for holding a substrate and pressing a surface of the substrate against the polishing surface to polish the surface of the substrate, and at least one optical measuring device disposed adjacent to the outer peripheral portion of the polishing table and below the polishing surface of the polishing table for measuring the thickness of a layer formed on the surface of the substrate. The polishing apparatus further has at least one notch formed in the peripheral portion of the polishing table. The notch allows light emitted from the optical measuring device to pass therethrough and be incident on the surface of the substrate and allows light reflected from the surface of the substrate to pass therethrough and be incident on the optical measuring device.